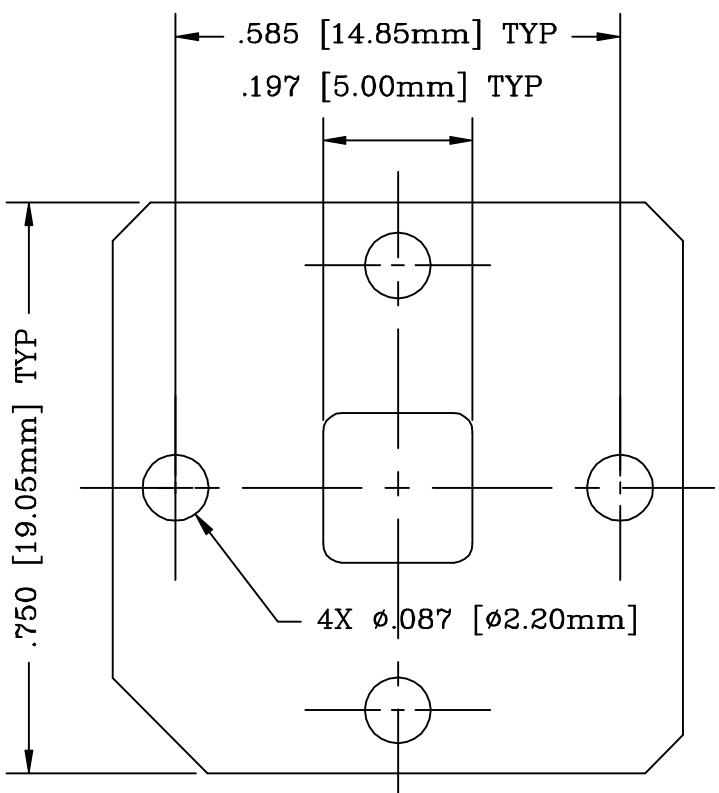
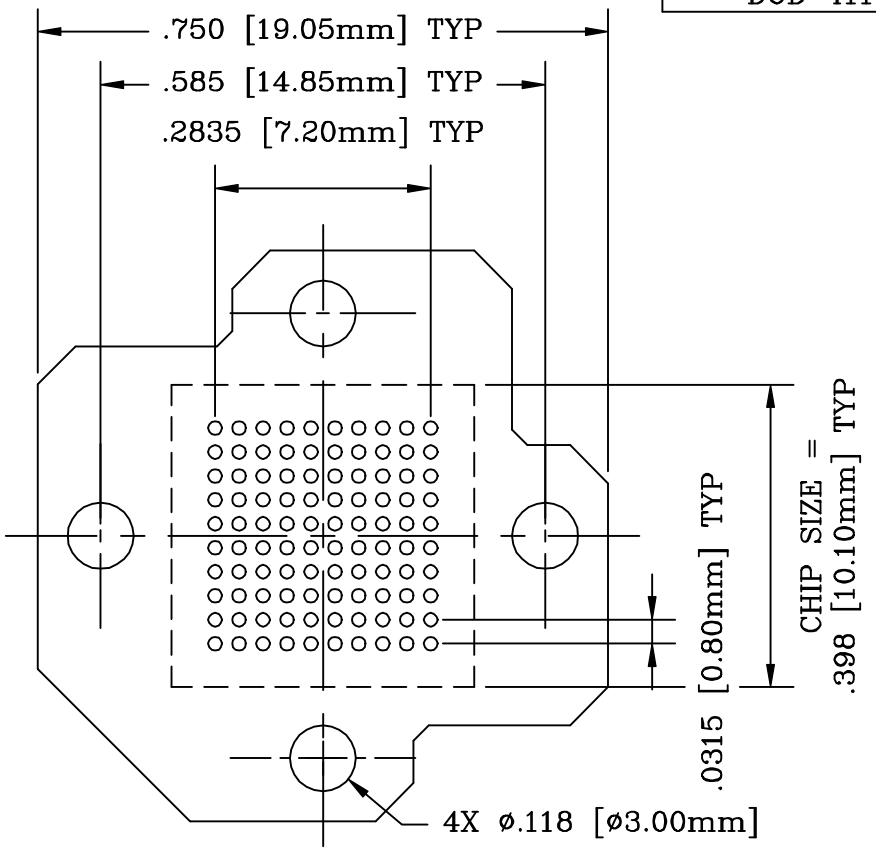


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	8/14/00	A.F.
B	UPDATED DIMMENSIONS	3/14/01	A.F.
C	UPDATED REC. PAD LAYOUT	10/09/02	H.N.

SKT1126
DOD 41126



RETENTION FRAME



SOCKET

RECOMMENDED PAD LAYOUT

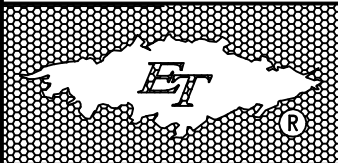
SOLDERTAIL STYLE	
REGULAR SMT STYLE XX = (-SM) YY = (-30)	RAISED SMT STYLE XX = (-RC) YY = (-29)
-30= standard SMT ("A" = .0236 [0.80mm]) -29= raised SMT ("A" = .110 [2.80mm])	
BALL DIAMETER FOR: -30(SM) = .0157 [0.40mm] TO .0217 [0.55mm] -29(RC) = .0157 [0.40mm] TO .0217 [0.55mm]	
BALL HEIGHT FOR: -30(SM) = .0098 [0.25mm] TO .0177 [0.45mm] -29(RC) = .0098 [0.25mm] TO .0177 [0.45mm]	

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET) YY = (-70)
PIN DIAMETER FOR: -70(ET) = .0114 [0.29mm]

PACKAGE SPECIFICATIONS

PIN COUNT	= 100
LEAD PITCH	= 0.80mm
GRID SIZE	= 10x10
PACKAGE SIZE	= 10.10mm

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.
 — VLSI and SMT ADAPTERS and ACCESSORIES —
 2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051
 TEL:(408)982-0660 FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 10/09/02	REVISION: C
CHECKED: Perry Munroe	DRAWN: Hanh Nguyen	ITEM: S-MBG-10-100-XXA
Scale 1:4	DO NOT SCALE DRAWING	DESCRIPTION: BPW-100-6BG010-YY

ASSEMBLY DRAWING

* All Dimmensions Are Nominal For A .0315 [0.80mm] Pitch BGA Package